

Product / Package Information

Package	TSOT
Body Size/Pitch	
Lead Count	6
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	5.19 E-03	87.3	873000	42.24		422427
Thermosets	Phenol Resin	Proprietary	2.67 E-04	4.5	45000	2.18		21775
Thermosets	Epoxy Resin 1	Proprietary	1.78 E-04	3.0	30000	1.45		14516
Thermosets	Epoxy Resin 2	Proprietary	1.78 E-04	3.0	30000	1.45		14516
Others	Others	Proprietary	1.19 E-04	2.0	20000	0.97		9678
Other inorganic materials	Carbon Black	1333-86-4	1.19 E-05	0.2	2000	0.10		968
Subtotal			5.94 E-03	100.0	1000000	48		483880

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	4.54 E-03	97.5	975000	36.96		369604
Copper & its alloys	Iron	7439-89-6	1.09 E-04	2.35	23500	0.89		8907
Copper & its alloys	Zinc	7440-66-6	5.58 E-06	0.12	1200	0.05		455
Copper & its alloys	Phosphorus	7723-14-0	1.40 E-06	0.03	300	0.01		114
Subtotal			4.65 E-03	100	1000000	38		379040

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	4.70 E-05	100	1000000	0.38		3829

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	5.96 E-04	100	1000000	4.85		48532

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.70 E-04	99.99	1000000	1.38		13848

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	8.00 E-04	100	1000000	6.52		65169

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	5.64 E-05	80.50	805000	0.46		4590
Other organic materials	Carbocyclic Acrylates	Proprietary	7.00 E-06	10.00	100000	0.06		570
Other organic materials	Bismaleimide resin	Proprietary	2.10 E-06	3.00	30000	0.02		171
Other organic materials	2-preponic acid, 2-methyl	68586-19-6	2.10 E-06	3.0	30000	0.02		171
Others	Additive	Proprietary	2.10 E-06	3.0	30000	0.02		171
Other organic materials	Dicumyl peroxide	80-43-3	3.50 E-07	0.5	5000	0.00		29
Subtotal			7.00 E-05	100.00	1000000	0.57		5702

Package Totals			Weight (g)	Percentage (%)	PPM			
			1.23 E-02	100	1000000			

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



ADI Proprietary

Product / Package Information	
Package	TSOT - COL
Body Size/Pitch	
LeadCount	6
Option	NiPdAu

Environmental Compliance Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.19 E-03	87.3	873000	44.40	443974
Thermosets	Phenol Resin	Proprietary	2.67 E-04	4.5	45000	2.29	22885
Thermosets	Epoxy Resin 1	Proprietary	1.78 E-04	3.0	30000	1.53	15257
Thermosets	Epoxy Resin 2	Proprietary	1.78 E-04	3.0	30000	1.53	15257
Others	Others	Proprietary	1.19 E-04	2.0	20000	1.02	10171
Other inorganic materials	Carbon Black	1333-86-4	1.19 E-05	0.2	2000	0.10	1017
Subtotal			5.94 E-03	100.0	1000000	51	508562

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.52 E-03	97.5	975000	38.74	387374
Copper & its alloys	Iron	7439-89-6	1.09 E-04	2.35	23500	0.93	9337
Copper & its alloys	Zinc	7440-66-6	5.57 E-06	0.12	1200	0.05	477
Copper & its alloys	Phosphorus	7723-14-0	1.39 E-06	0.03	300	0.01	119
Subtotal			4.64 E-03	100	1000000	40	397307

Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	5.41 E-05	90.91	909091	0.46	4628
Precious metals	Palladium	7440-05-3	4.70 E-06	7.91	79051	0.04	402
Precious metals	Gold	7440-57-5	7.05 E-07	1.19	11858	0.01	60
Subtotal			5.95 E-05	100.00	1000000	0.51	5090

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.70 E-04	99.99	1000000	1.46	14555

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	8.00 E-04	100	1000000	6.85	68493

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Epoxy Resin	Proprietary	2.17 E-05	31	310000	0.19	1858
Other inorganic materials	Metal Oxide	Proprietary	2.17 E-05	31	310000	0.19	1858
Other inorganic materials	Glycol Ethers	Proprietary	1.54 E-05	22	220000	0.13	1318
Other inorganic materials	Silica	Proprietary	5.60 E-06	8	80000	0.05	479
Others	Curing agent & hardener	Proprietary	5.60 E-06	8	80000	0.05	479
Subtotal			7.00 E-05	100	1000000	0.60	5993

Package Totals	Weight (g)	Percentage (%)	PPM
	1.17 E-02	100	1000000

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